Silicon Carbide Schottky Diode

650 V, 10 A

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 49 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery
- AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

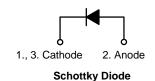
Applications

- Automotive HEV–EV Onboard Chargers
- Automotive HEV–EV DC–DC Converters



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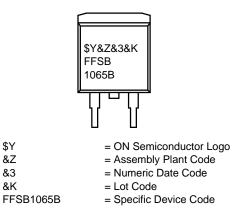
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D²PAK-3 (TO-263, 3-LEAD) CASE 418AJ

MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter	Value	Unit	
V _{RRM}	Peak Repetitive Reverse Voltage	650	V	
E _{AS}	Single Pulse Avalanche Energy (Note 1)	49	mJ	
١ _F	Continuous Rectified Forward Current @ T _C < 25°C		27	А
	Continuous Rectified Forward Current @ T_C <	10		
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	650	А
		T _C = 150°C, 10 μs	570	А
I _{F,SM}	Non-Repetitive Forward Surge Current $T_{C} = 25^{\circ}C$	Half-Sine Pulse, t _p = 8.3 ms	45	A
Ptot Power Dissipation	Power Dissipation $T_C = 25^{\circ}C$	$T_{C} = 25^{\circ}C$	79	W
		$T_{\rm C} = 150^{\circ}{\rm C}$	13	W
TJ, T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. E_{AS} of 49 mJ is based on starting $T_J = 25^{\circ}$ C, L = 0.5 mH, I_{AS} = 14 A, V = 50 V.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
R_{\thetaJC}	Thermal Resistance, Junction to Case, Max	1.9	°C/W

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	I _F = 10 A, T _C = 25°C	-	1.38	1.7	V
		I _F = 10 A, T _C = 125°C	-	1.6	2.0	
		I _F = 10 A, T _C = 175°C	-	1.72	2.4	
I _R	Reverse Current	$V_{R} = 650 \text{ V}, \text{ T}_{C} = 25^{\circ}\text{C}$	-	0.5	40	μΑ
		$V_R = 650 \text{ V}, \text{ T}_C = 125^{\circ}\text{C}$	-	1	80	
		$V_R = 650 \text{ V}, \text{ T}_C = 175^{\circ}\text{C}$	-	2	160	
Q _C	Total Capacitive Charge	V = 400 V	-	25	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	421	-	pF
		V _R = 200 V, f = 100 kHz	-	46	-]
		V _R = 400 V, f = 100 kHz	-	35	-]

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping*
FFSB1065B-F085	FFSB1065B	D ² PAK–3 (Pb-Free / Halogen Free)	800 / Tape & Reel

* For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

TYPICAL CHARACTERISTICS

(T_J = 25°C unless otherwise noted)

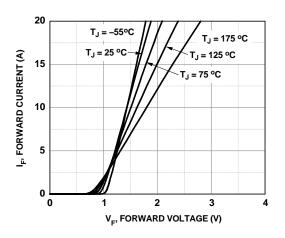
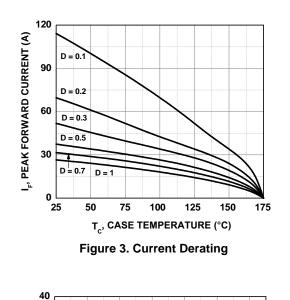


Figure 1. Forward Characteristics



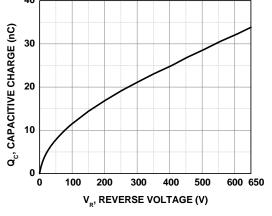


Figure 5. Capacitive Charge vs. Reverse Voltage

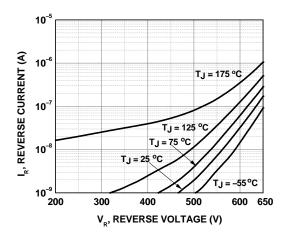
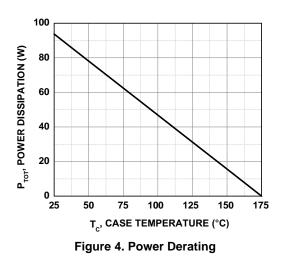


Figure 2. Reverse Characteristics



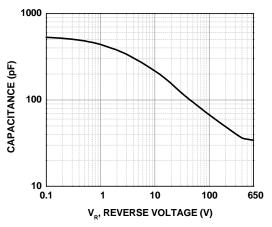


Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS

 $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

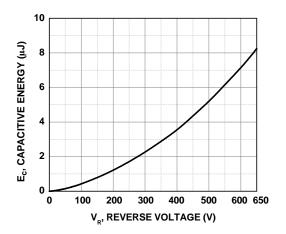


Figure 7. Capacitance Stored Energy

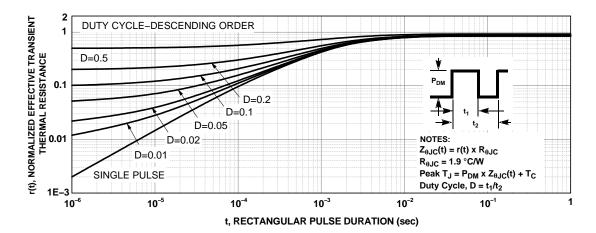


Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

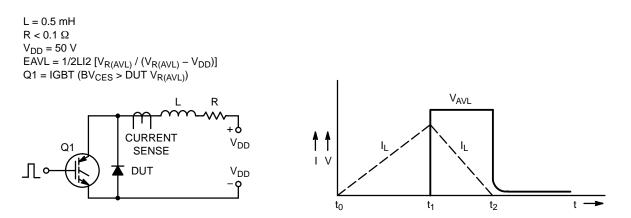
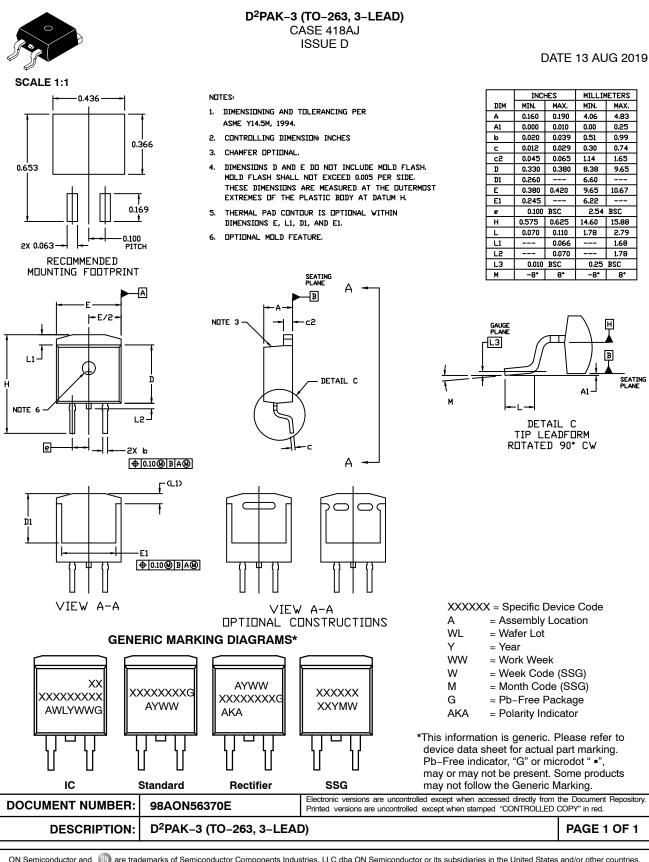


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS





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